



Qualcomm AI250

Dragonfly

2027

OVERVIEW

— FP32 TFLOPS	768 GB VRAM HBC Gen 1	— Memory Bandwidth	— TDP
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PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
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MEMORY SPECIFICATIONS

Capacity	768 GB
Type	HBC Gen 1
Bandwidth	—
Interface Width	—

POWER & EFFICIENCY

TDP	—
Est. Max Power	—
FP32 Efficiency	—
FP16 Efficiency	—

HARDWARE DETAILS

Vendor: Qualcomm	Architecture: Dragonfly	Process Node: —
Form Factor: —	Launch Year: 2027	

INTERCONNECT

GPU-to-GPU: PCIe 6.0 scale-up /
Ethernet with RoCE scale-out